

CALL FOR PAPERS – ISPD 2019

ACM International Symposium on Physical Design
with a tribute to Professor Alberto Sangiovanni-Vincentelli

<http://www.ispd.cc>

April 14 -April 17, 2019

Bay Area, California, USA

Sponsored by ACM SIGDA with Technical Co-sponsorship from IEEE CAS

The International Symposium on Physical Design provides a premier forum to exchange ideas and promote research on critical areas related to the physical design of VLSI systems. All aspects of physical design, including its interactions with architecture, behavioral- and logic-level synthesis, and back-end performance analysis and verification are within the scope of the symposium. Target domains include semi-custom and full-custom ICs, regular fabrics, FPGAs, and systems-on-chip/systems-in-package. Following its twenty-seven predecessors, the 2019 symposium will highlight key new directions and leading-edge theoretical and experimental contributions to the field. The ACM Press will publish accepted papers in the Symposium proceedings. ISPD will recognize excellent contributions through a Best Paper Award. Topics of interest include but are not limited to:

Floorplanning and interconnect planning
Partitioning, placement and routing
Physical design for manufacturability and yield
Synthesis optimizations within physical design
Estimation and modeling
Timing and crosstalk issues in physical design
Special structures for clocking and power networks
Physical design for emerging process technologies

Interactions with system and logic level design
Analysis and management of power dissipation
Management of design data and constraints
New physical design methodologies
Physical design for FPGAs
Circuit performance measurements in a PD context
Parallel/hardware acceleration algorithms for PD
Hardware security related physical design

IMPORTANT DATES	Title and abstract submission deadline	October 1, 2018
	Full manuscript submission deadline	October 8, 2018
	Acceptance notification	November 11, 2018
	Camera-ready paper due	End of January, 2019

SUBMISSION OF PAPERS

All papers must be submitted electronically via <https://easychair.org/conferences/?conf=ispd2019>. Details will be posted on the website <http://www.ispd.cc>. Potential authors will be required to submit full-length, original, unpublished papers (a maximum of 8 pages in ACM conference format) along with an abstract of at most 200 words and contact author information (name, mailing address, telephone/fax, e-mail). *Previously published papers or papers currently submitted for publication to other conferences/journals will not be considered. If one or more related papers have been previously published or have been concurrently submitted elsewhere for publication, the authors should clearly state the differences between these papers and the current submission. All submitted papers will be under blind reviews, and thus they must not include name(s) or affiliation(s) of the author(s) anywhere in the manuscripts. Failure to comply with these requirements will result in automatic rejection.*

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